

What is claimed is:

- 1    1. An alignment weight, comprising:  
2        a body having a first opposing surface and a second opposing surfaces; and  
3        a number of depressions formed in the first opposing surface so as to receive  
4 pins of a floating pin field when placed on the floating pin field during connection of  
5 the floating pin field to a printed circuit board, wherein selected ones of the number  
6 of depressions are configured to receive only one of the pins.
- 1    2.     The alignment weight of claim 1, wherein the number of depressions are  
2 formed in rows along a perimeter of the body.
- 1    3.     The alignment weight of claim 1, wherein the body comprises a material that  
2 exhibits substantially no warping during a solder reflow process.
- 1    4.     The alignment weight of claim 1, wherein the body further includes a  
2 number of holes that pass through a thickness of the body.
- 1    5.     The alignment weight of claim 4, wherein the holes are disposed in a center  
2 region of the first opposing surface of the body.
- 1    6.     The alignment weight of claim 1, wherein the depressions have a diameter at  
2 a surface of the body that is greater than a diameter of the depression inside the  
3 body.
- 1    7. An alignment weight, comprising:  
2        a body having a first opposing surface and a second opposing surfaces; and  
3        a plurality of depressions formed in the first opposing surface so as to  
4 receive pins of a floating pin field when placed on the floating pin field during  
5 connection of the floating pin field to a printed circuit board, wherein each of the  
6 plurality of depressions are configured to receive only one of the pins of the floating  
7 pin field, and wherein the body has a weight sufficient to provide a downward force  
8 to secure the pins of the floating pin field in place during a solder reflow process and  
9 to maintain the pins of the floating pin field in a substantially straight-up alignment.

- 1 8. The alignment weight of claim 1, wherein some of the plurality of  
2 depressions have an inner diameter smaller than an outer diameter.
- 1 9. The alignment weight of claim 1, wherein some of the plurality of  
2 depressions have an interior angle of less than about 90 degrees.
- 1 10. The alignment weight of claim 1, wherein some of the plurality of  
2 depressions are substantially circular.
- 1 11. An apparatus, comprising:  
2 an alignment weight;  
3 a circuit board; and  
4 a plurality of pins adjacent the circuit board and a corresponding plurality of  
5 depressions in the alignment weight.
- 1 12. The apparatus of claim 11, further comprising:  
2 a field carrier coupled to the plurality of pins.
- 1 13. The apparatus of claim 11, wherein the alignment weight further includes a  
2 plurality of passages that pass through a thickness of the alignment weight.
- 1 14. The apparatus of claim 13, wherein the plurality of passages are disposed in  
2 a center region of a first opposing surface of the alignment weight.
- 1 15. The apparatus of claim 11, wherein the alignment weight comprises a body  
2 having a first opposing surface and a second opposing surfaces, wherein the body  
3 has a plurality of passages extending from the first opposing surface to the second  
4 opposing surface and located in a center region of the first opposing surface,  
5 wherein the corresponding plurality of depressions are disposed in rows about a  
6 perimeter of the first opposing surface and configured to receive only one pin of the  
7 plurality of pins.
- 1 16. The apparatus of claim 11, wherein some of the corresponding plurality of  
2 depressions have a diameter at a surface of the body that is greater than a diameter  
3 of inside the body.